

Title (en)  
Enamelled wire with high resistance to partial discharges

Title (de)  
Lackierter Draht mit hoher Teilentladungsfestigkeit

Title (fr)  
Fil émaillé de résistance élevée aux décharges partielles

Publication  
**EP 0860835 A1 19980826 (FR)**

Application  
**EP 98400405 A 19980219**

Priority  
FR 9702166 A 19970224

Abstract (en)  
The enamelled wire (1) comprises a conductor and at least two layers (2,3,4) of enamelling, one of which is charged with particles having a weak electrical conductivity. The wire is surrounded by the enamelled layers, the outermost of which (4) is not charged with the particles but consists of a thermo-adhesive resin. The layer (3) immediately beneath the outside layer is the layer which contains the particles having a low electrical conductivity. The innermost layer (2) may also be charged with these conductive particles.

Abstract (fr)  
Le fil émaillé comporte un conducteur et au moins deux couches d'émaillage dont au moins l'une d'elles est chargée de particules faiblement conductrices. Il est caractérisé en ce que la couche d'émaillage la plus extérieure (4) est non chargée desdites particules et constituée en une résine thermo-adhérente et la couche (3) directement sous-jacente à celle-ci est en résine chargée desdites particules. Application : fil émaillé de bobinage.  
<IMAGE>

IPC 1-7  
**H01B 3/30**

IPC 8 full level  
**H01F 27/28** (2006.01); **H01B 3/30** (2006.01); **H01B 7/02** (2006.01)

CPC (source: EP US)  
**H01B 3/308** (2013.01 - EP US); **Y10T 428/2947** (2015.01 - EP US)

Citation (search report)  
• [A] EP 0447789 A1 19910925 - ALCATEL CUIVRE [FR]  
• [A] EP 0568415 A1 19931103 - UDD FIM S A [FR]  
• [A] EP 0287813 A2 19881026 - ASEA BROWN BOVERI [SE]  
• [A] US 4388371 A 19830614 - BOLON DONALD A, et al

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